

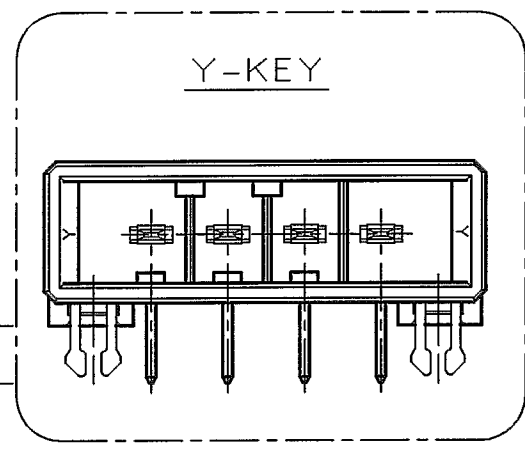
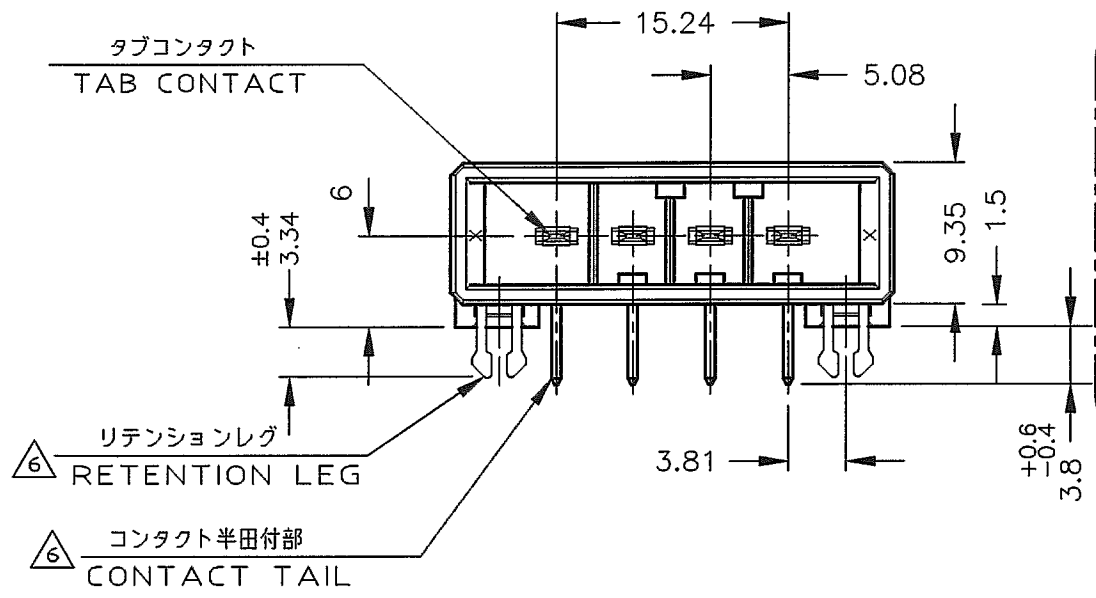
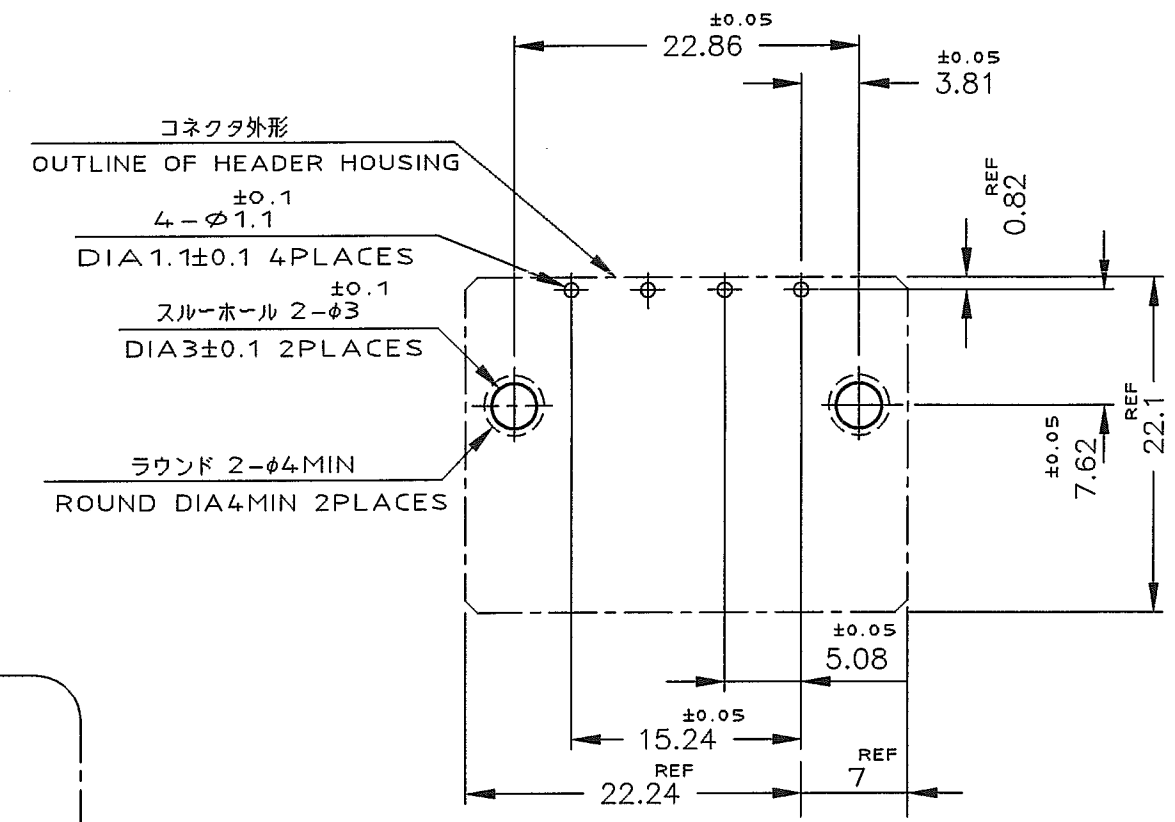
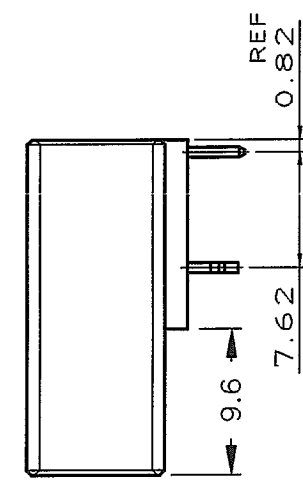
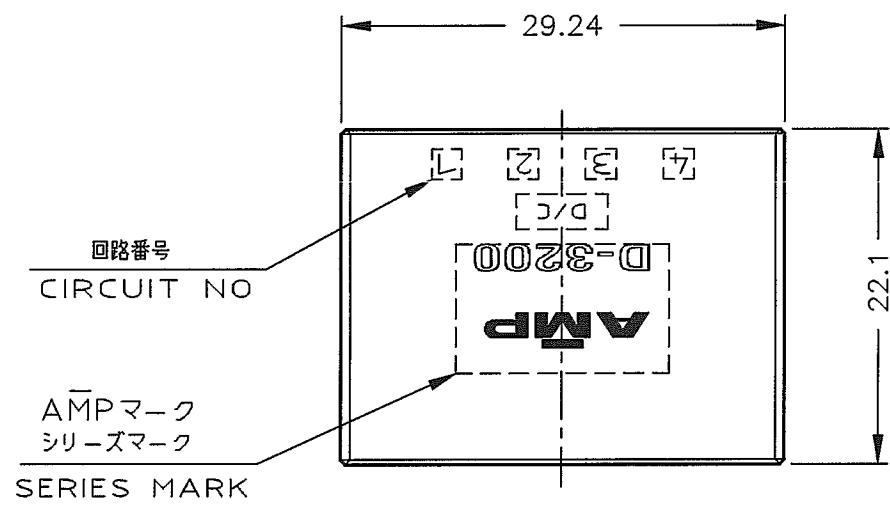
NUMBER 179277



METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



推奨基板取付け穴寸法
PC 基板厚: 1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER NI PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER NI PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地
接触部: 0.38 μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 0.76 μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MINスズめっき
- めっき: リテンションレグとコンタクト半田付部
ニッケル下地の上に半田めっき
- めっき: リテンションレグとコンタクト半田付部: ニッケル下地の上にスズめっき

△6	△4	2-179277-5	Y
△6	△3	2-179277-3	Y
△6	△2	2-179277-2	Y
△6	△4	1-179277-5	X
△6	△3	1-179277-3	X
△6	△2	1-179277-2	X
(FINISH)	製品番号 (PART NO.)	KEY	

D	REVISED (FJDO-0039-03)	T.S.S.M.	8/3	
C	REVISED (FJDO-0097-03)	T.S.S.M.	4/15	
B	REVISED (FJ00-1335-97)	K.I.I.H.	5/SEP	
A	REVISED (FJ00-5532-96)	K.I.Y.I.	1-7	
O	RELEASED (FJ00-0736-93)	NM	12-13	
LTR	REVISION RECORD	DR	CHK	DATE

Copyright © 1993 Tyco Electronics AMP K.K. ALL RIGHTS RESERVED.		NAME 4 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200	
WIRE RANGE mm ² (AWG -)	INSULATION DIA mmφ	MATERIAL SEE NOTE 注記参照	FINISH SEE NOTE 注記参照
DR. N. Matsubara 10 DEC 93	DE. N. Matsubara 10 DEC 93	CHK. S. MANABE 13 DEC 93	APP. S. MANABE 13 DEC 93

Tyco Electronics		Tyco Electronics AMP K.K. Kawasaki, Japan	
一般公差 (GENERAL TOLERANCE)	SIZE A3	LOC J	NUMBER C-179277
10mm以下: ±0.3 10mm超 30mm以下: ±0.4 30mm超 100mm以下: ±0.5 角 度: ±3'	SCALE 2-1	REV. D	SHEET 1 OF 1